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(12) **United States Design Patent**
**Hasegawa et al.**

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(54) **POWER SEMICONDUCTOR DEVICE**

(71) Applicant: **MITSUBISHI ELECTRIC CORPORATION**, Tokyo (JP)

(72) Inventors: **Maki Hasegawa**, Tokyo (JP); **Masahiro Kato**, Tokyo (JP); **Shinya Nakagawa**, Tokyo (JP); **Hisashi Kawafuji**, Tokyo (JP); **Toru Iwagami**, Tokyo (JP)

(73) Assignee: **Mitsubishi Electric Corporation**, Tokyo (JP)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** ................................................ **13-03**

(52) **U.S. Cl.**
USPC ........................................................ **D13/182**

(58) **Field of Classification Search**
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CPC ............. H01L 21/00; H01L 21/02433; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/17151; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905; H01L 2224/08054; H01L 23/58; H05B 41/14; H02B 6/4201; G02B 6/4256; G02B 6/4257; G02B 6/4261; G02B 6/4262; G02B 6/42; G02B 6/4281; H05K 1/14; H05K 1/141; H05K 1/142; H05K 1/144; H05K 1/18; H05K 1/181; H05K 1/182; H05K 1/026; H05K 1/0228; H05K 1/0245; H05K 1/0236; H05K 1/0263
See application file for complete search history.

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*Primary Examiner* — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Studebaker & Brackett PC

(57) **CLAIM**

The ornamental design for a power semiconductor device, as shown and described.

**DESCRIPTION**

FIG. **1** is a front, right and bottom perspective view of a power semiconductor device, showing our new design;
FIG. **2** is a rear, left and top perspective view thereof;
FIG. **3** is a front view thereof;
FIG. **4** is a rear view thereof;
FIG. **5** is a left side view thereof;
FIG. **6** is a right side view thereof;
FIG. **7** is a top plan view thereof; and,
FIG. **8** is a bottom plan view thereof.

The broken lines shown represent unclaimed subject matter of a power semiconductor device and form no part of the claimed design.

**1 Claim, 8 Drawing Sheets**

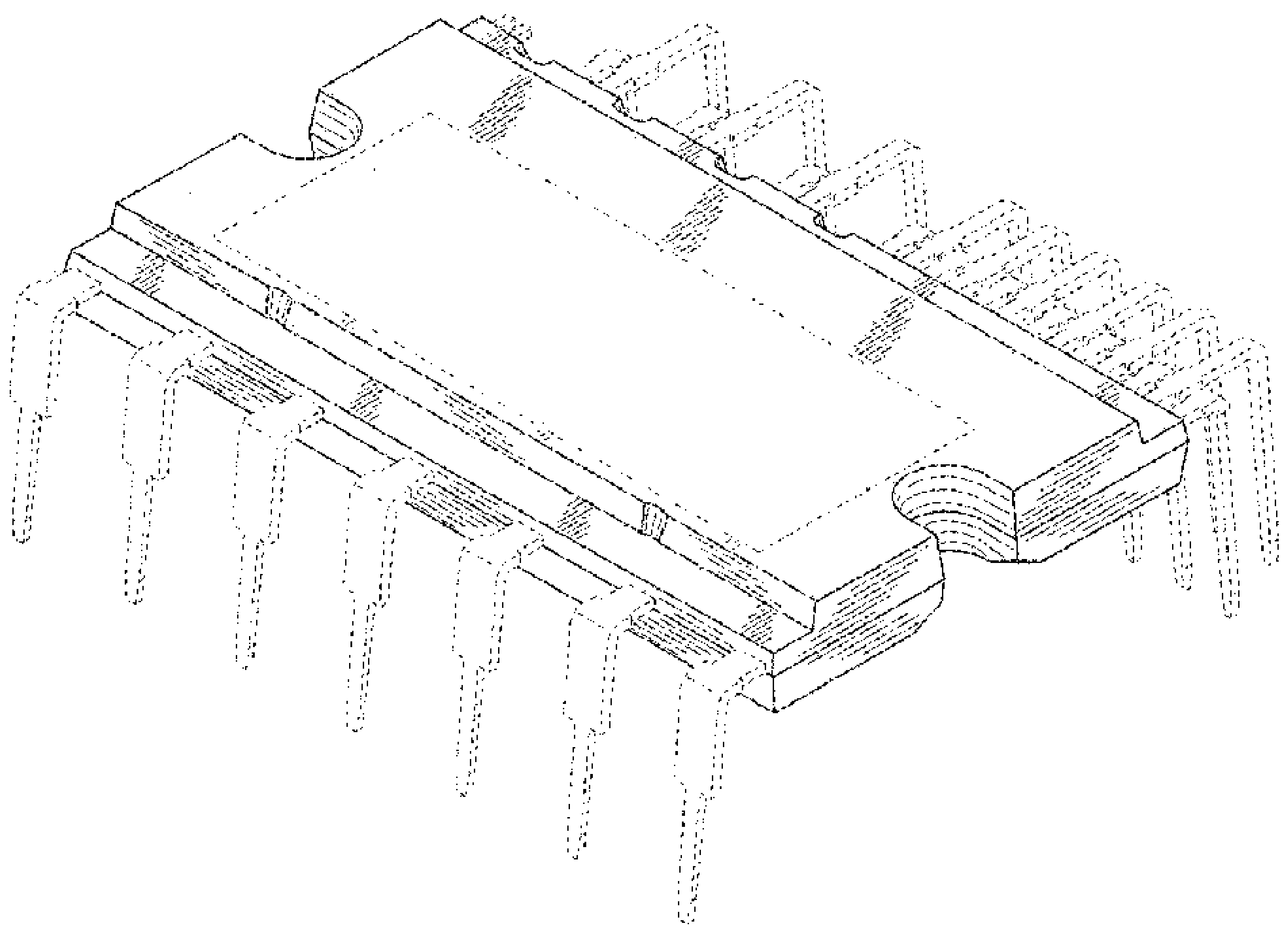

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*FIG. 1*

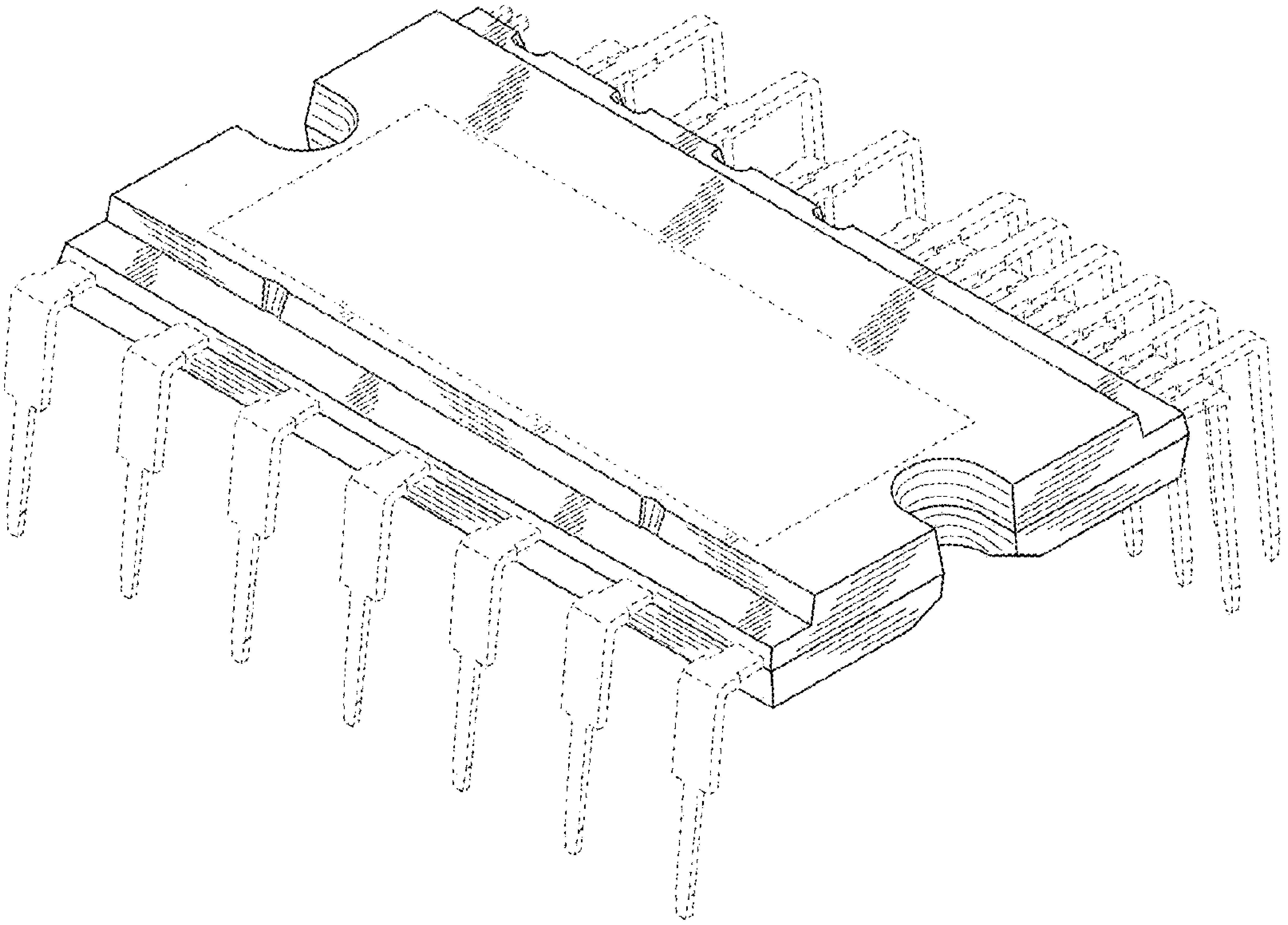

*FIG. 2*

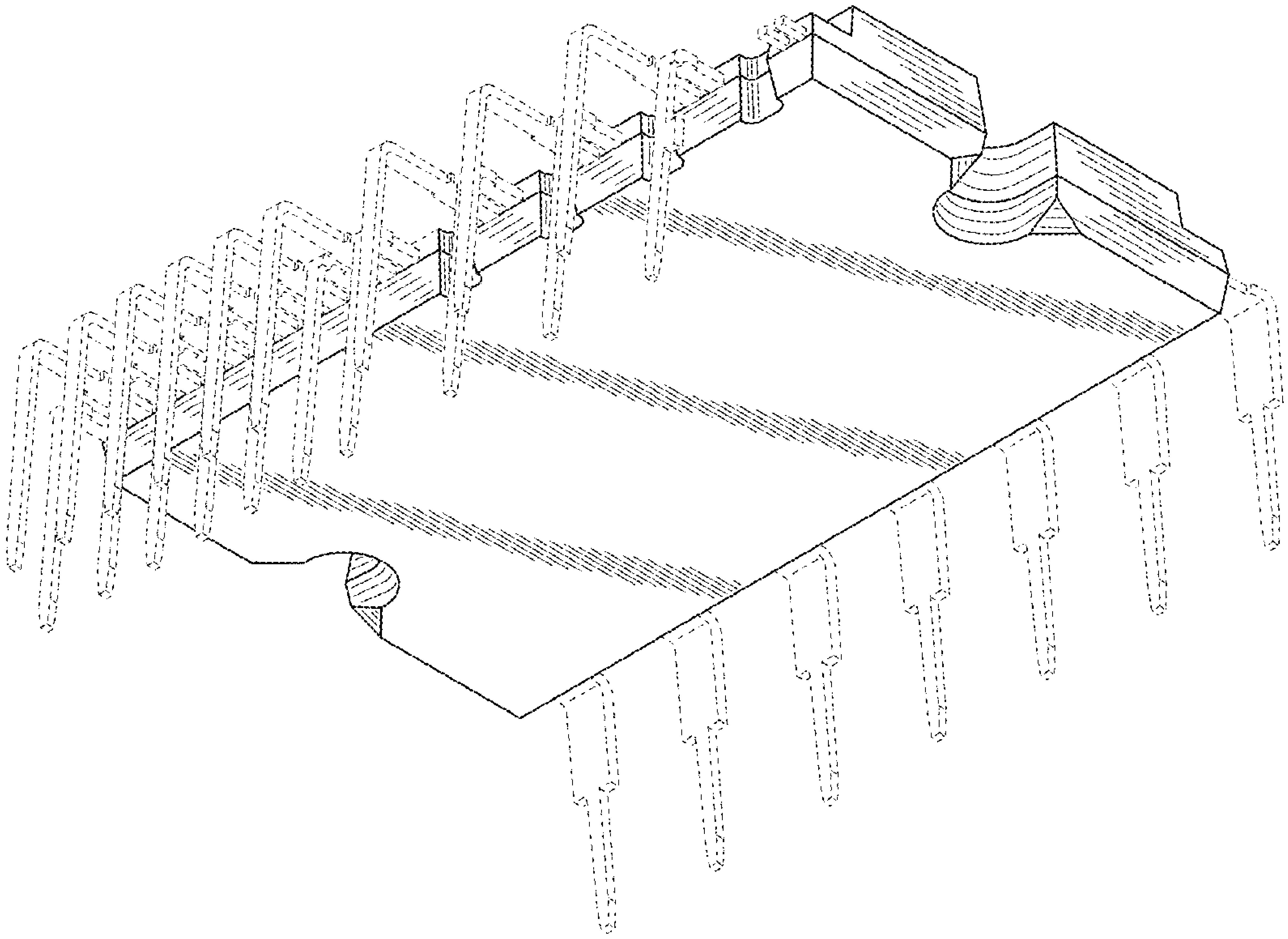

FIG. 3

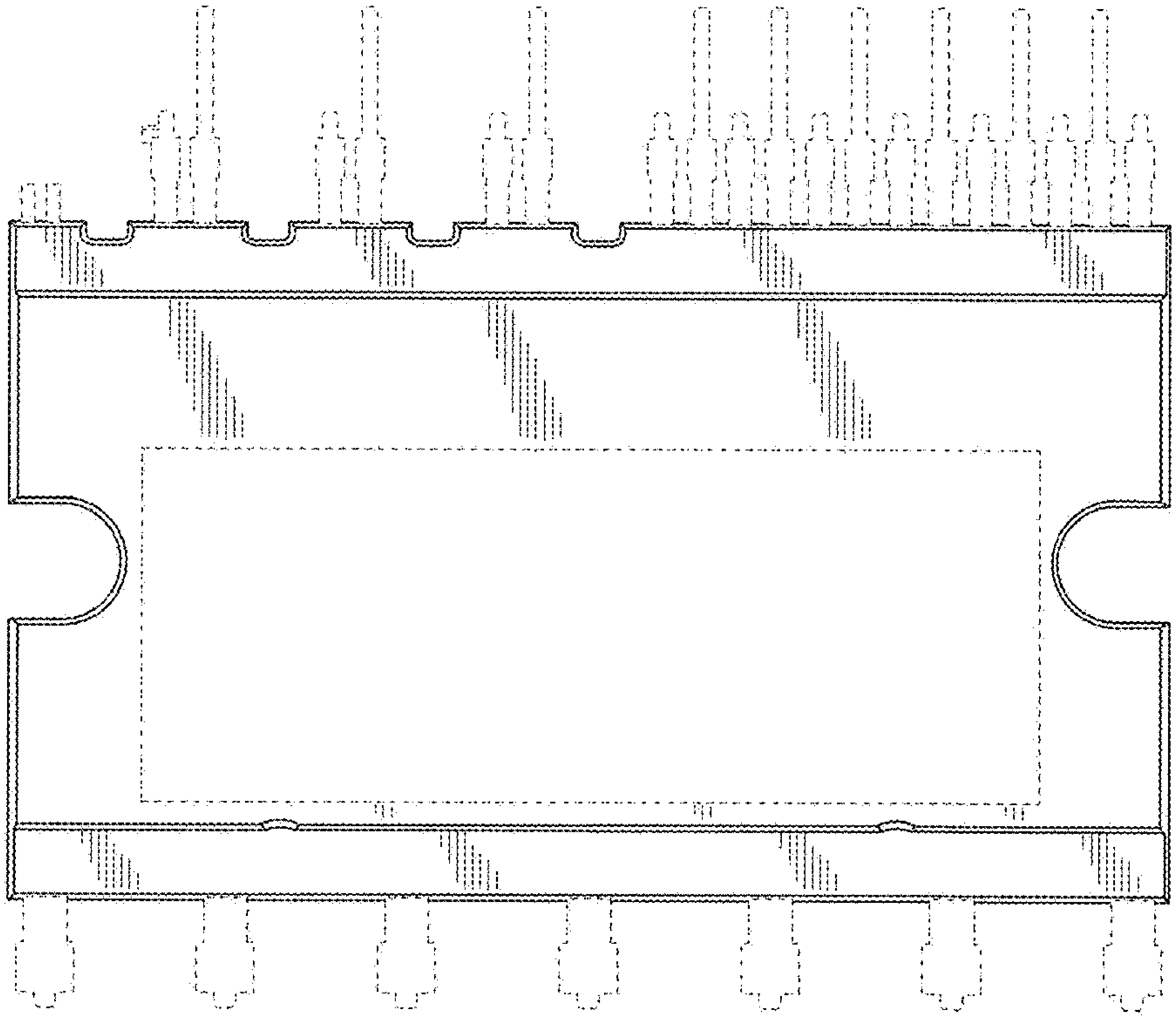

*FIG. 4*

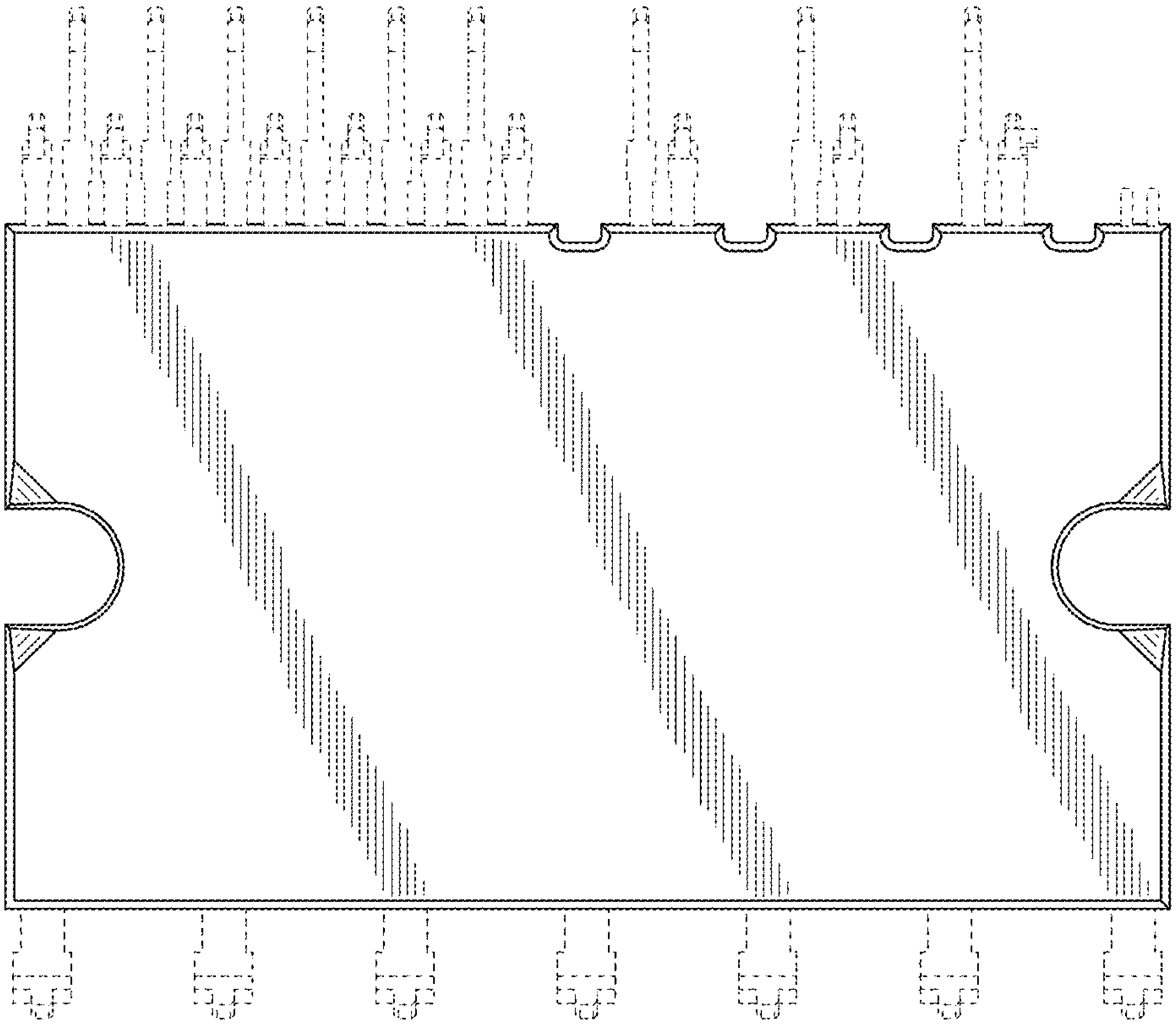

*FIG. 5*

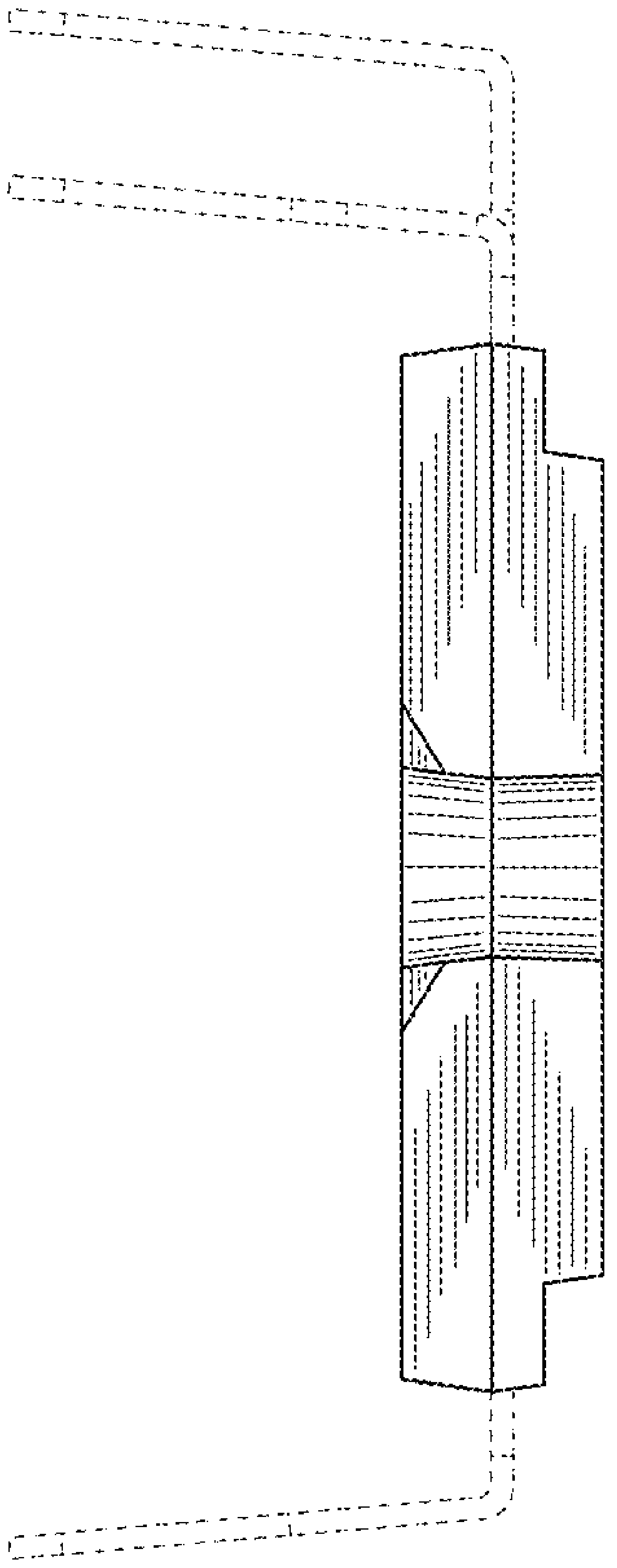

FIG. 6

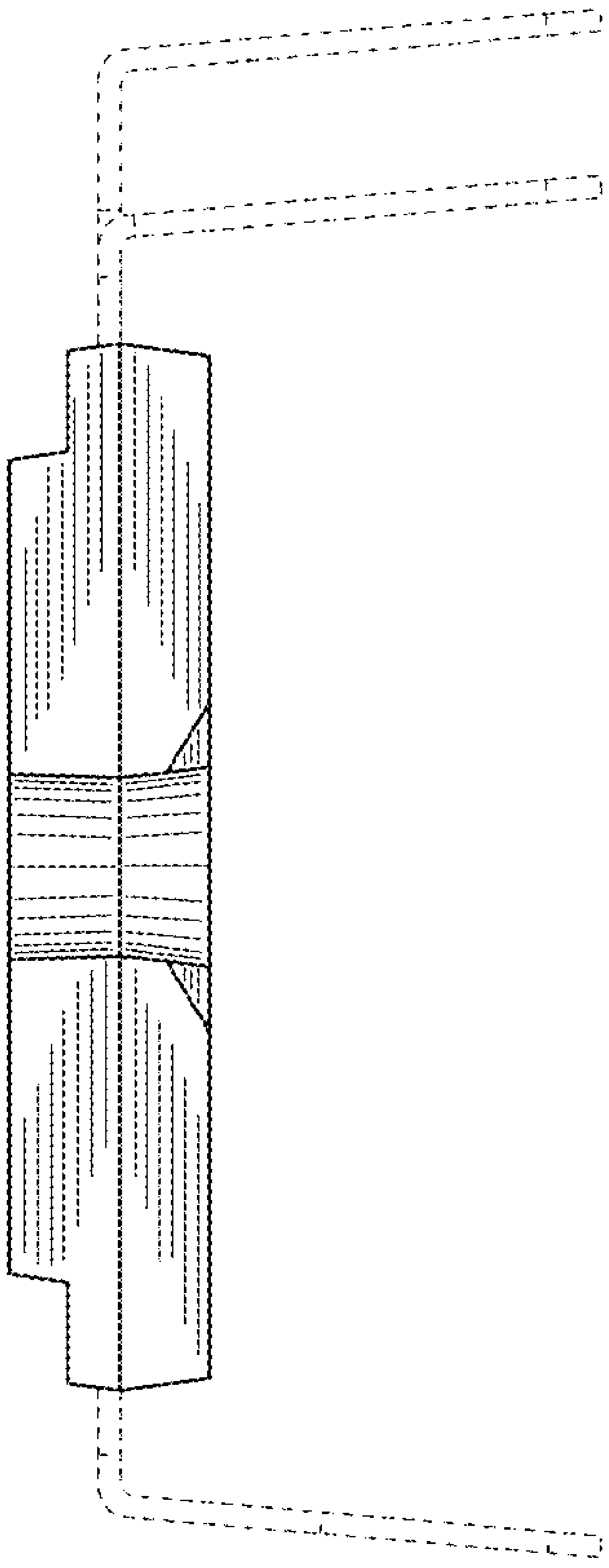

*FIG. 7*

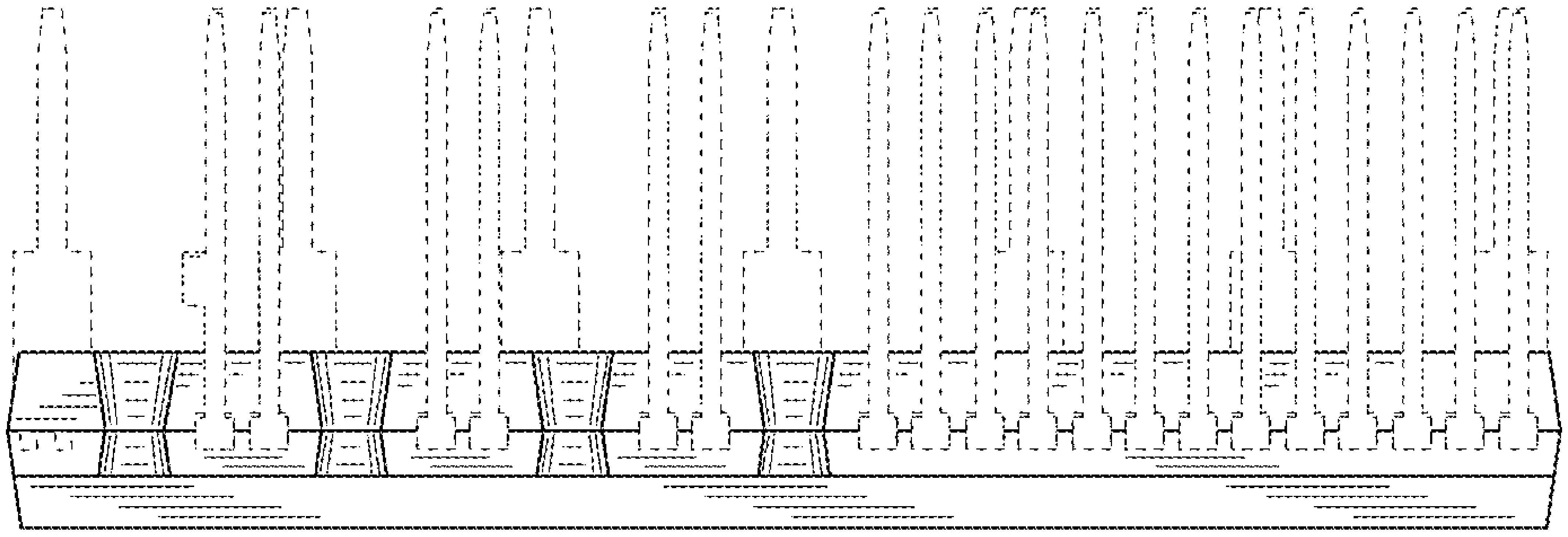

*FIG. 8*